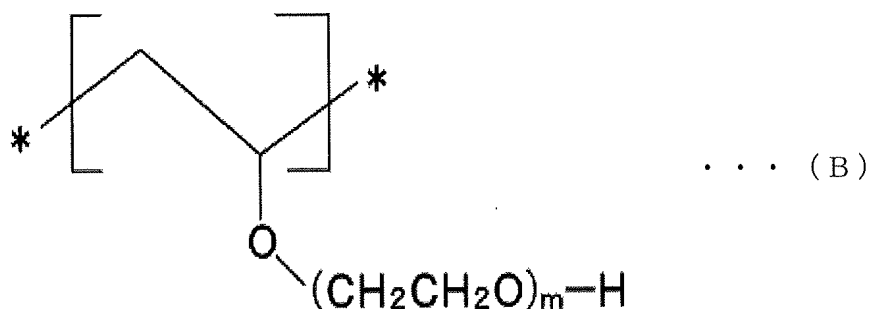
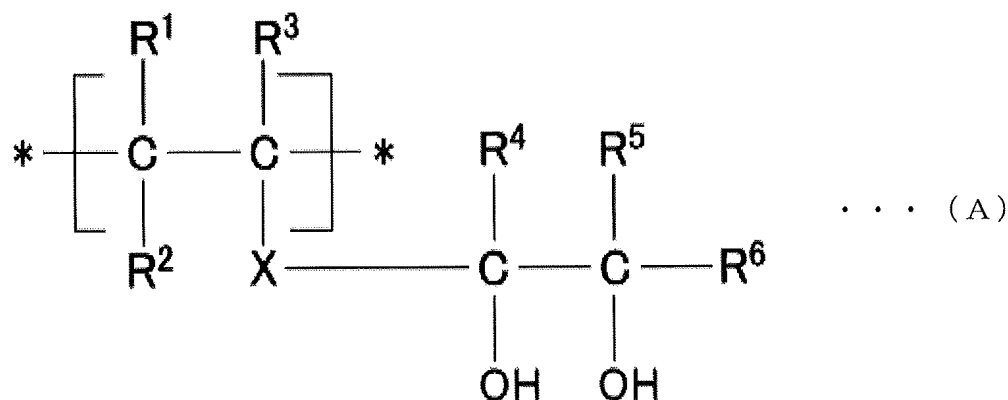


ABSTRACT

A polishing composition is provided that can reduce small defects and haze on a semiconductor wafer after polishing. A polishing composition includes: an abrasive; a basic compound; a vinyl alcohol-based resin having a 1,2-diol structural unit represented by the following general formula, (A); and a vinyl alcohol-based resin having a polyoxyethylene structural unit represented by the following general formula, (B):



Here, each of R¹, R² and R³ independently indicates a hydrogen atom or an organic group, X indicates a single bond or a joining chain, and each of R⁴, R⁵ and R⁶ independently indicates a hydrogen atom or an organic group. m is an integer ranging from 1 to 1,000.

[Figure 6]